PRODUCT FAMILY DATA SHEET

Cree[®] XLamp[®] MX-3 LEDs



PRODUCT DESCRIPTION

The Cree XLamp[®] MX-3 LED provides the proven lighting-class performance and reliability of Cree XLamp LEDs in a flat-top PLCC package. The XLamp MX-3 LED continues Cree's history of innovation in LEDs for lighting applications with a wide viewing angle, unlimited floor life, uniform light output without secondary optics and electrically neutral thermal path.

The XLamp MX-3 LED brings high performance and quality of light to a wide range of lighting applications, including linear lighting, LED light bulbs, fluorescent retrofits and retail-display lighting.

FEATURES

- Available in white (2600 K to 8300 K CCT)
- Maximum drive current: 500 mA
- Wide viewing angle: 120°
- Electrically neutral thermal path
- Qualification at maximum drive current
- RoHS- and REACh-compliant
- UL-recognized component (E349212)



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CHARACTERISTICS

Characteristics	Unit	Minimum	Typical	Maximum
Thermal resistance, junction to solder point	°C/W		11	
Viewing angle (FWHM)	degrees		120	
Temperature coefficient of voltage	mV/ °C		-2.7	
ESD classification (HBM per Mil-Std-883D)			Class 2	
DC forward current	mA			500
Reverse voltage	V			-5
Reverse current	mA			-0.1
Forward voltage (@ 350 mA)	V		3.7	4.0
LED junction temperature	°C			150

FLUX CHARACTERISTICS (T_j = 25 °C)

The following table provides several base order codes for XLamp MX-3 LEDs. It is important to note that the base order codes listed here are a subset of the total available order codes for the product family. For more order codes, as well as a complete description of the order-code nomenclature, please consult the XLamp MX Family LED Binning and Labeling document.

Color	CCT Range		Min. Lumi	ler Codes inous Flux 350 mA	Calculated Min. Luminous Flux (Im) @ 300 mA*	Order Code
	Min.	Max.	Group	Flux (lm)	Flux (lm)	
Cool White 5000 K	E000 K	000 K 8300 K	R2	114	100	MX3AWT-A1-0000-000E51
	K 8300 K	Q5	107	93.9	MX3AWT-A1-0000-000D51	
Warm White	3700 K	4300 K	Q4	100	87	MX3AWT-A1-0000-000CE5
	2600 K	3700 K	Q3	93.9	82	MX3AWT-A1-0000-000BE7

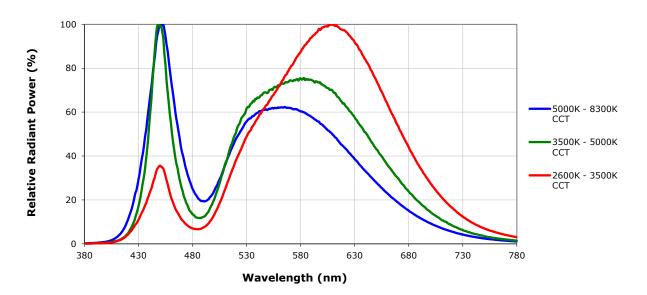
* Calculated values for reference purposes only.

Notes:

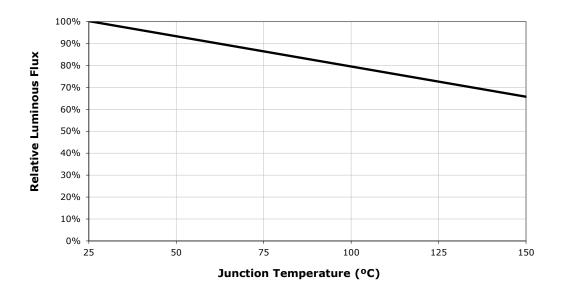
- Cree maintains a tolerance of ±7% on flux and power measurements, ±0.005 on chromaticity (CCx, CCy) measurements and ±2 on CRI measurements. See the Measurements section (page 7).
- Typical CRI for Cool White (4300 K 8300 K CCT) is 75.
- Typical CRI for Warm White (2600 K 4300 K CCT) is 80.



RELATIVE SPECTRAL POWER DISTRIBUTION

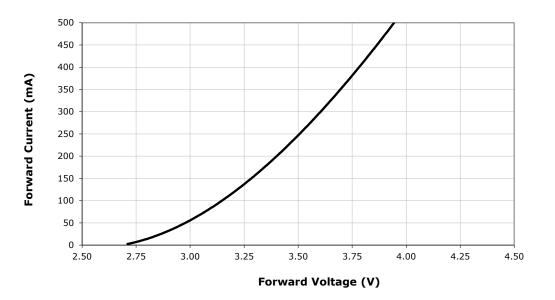


RELATIVE FLUX VS. JUNCTION TEMPERATURE (I_F = 350 mA)

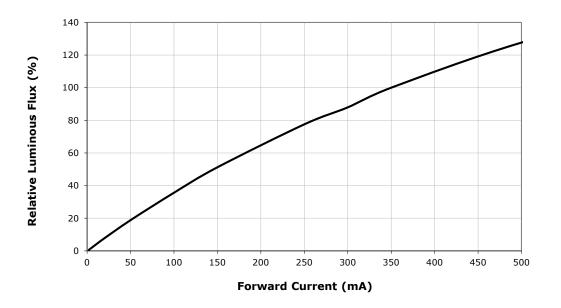




ELECTRICAL CHARACTERISTICS (T₁ = 25 °C)

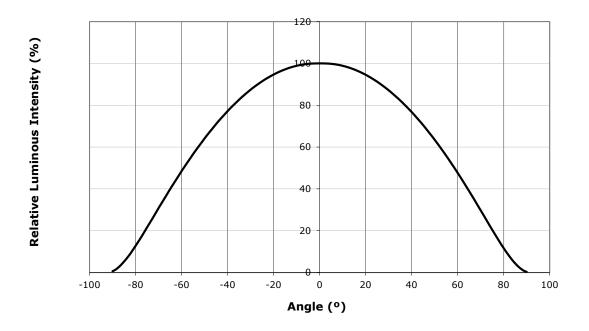


RELATIVE FLUX VS. CURRENT (T₁ = 25 °C)



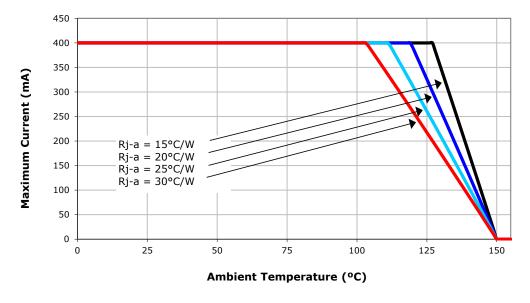


TYPICAL SPATIAL DISTRIBUTION



THERMAL DESIGN

The maximum forward current is determined by the thermal resistance between the LED junction and ambient. It is crucial for the end product to be designed in a manner that minimizes the thermal resistance from the solder point to ambient in order to optimize lamp life and optical characteristics.



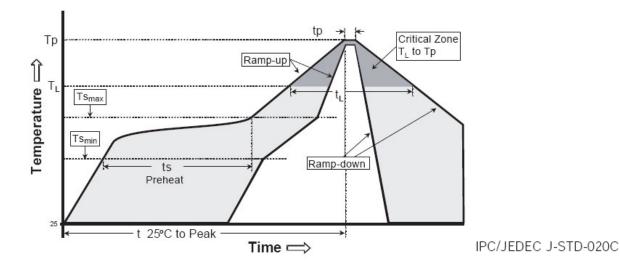
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REFLOW SOLDERING CHARACTERISTICS

In testing, Cree has found XLamp XM-L LEDs to be compatible with JEDEC J-STD-020C, using the parameters listed below. As a general guideline, Cree recommends that users follow the recommended soldering profile provided by the manufacturer of solder paste used.

Note that this general guideline may not apply to all PCB designs and configurations of reflow soldering equipment.



Profile Feature	Lead-Based Solder	Lead-Free Solder
Average Ramp-Up Rate (Ts _{max} to Tp)	3 °C/second max.	3 °C/second max.
Preheat: Temperature Min (Ts _{min})	100 °C	150 °C
Preheat: Temperature Max (Ts _{max})	150 °C	200 °C
Preheat: Time (ts _{min} to ts _{max})	60-120 seconds	60-180 seconds
Time Maintained Above: Temperature (T_L)	183 °C	217 °C
Time Maintained Above: Time $(\boldsymbol{t}_{\!\scriptscriptstyle L})$	60-150 seconds	60-150 seconds
Peak/Classification Temperature (Tp)	215 °C	260 °C
Time Within 5 °C of Actual Peak Temperature (tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to the topside of the package, measured on the package body surface.

NOTES

Measurements

The luminous flux, radiant power, chromaticity and CRI measurements in this document are binning specifications only and solely represent product measurements as of the date of shipment. These measurements will change over time based on a number of factors that are not within Cree's control and are not intended or provided as operational specifications for the products. Calculated values are provided for informational purposes only and are not intended as specifications.

Lumen Maintenance

Cree now uses standardized IES LM-80-08 and TM-21-11 methods for collecting long-term data and extrapolating LED lumen maintenance. For information on the specific LM-80 data sets available for this LED, refer to the public LM-80 results document.

Please read the Long-Term Lumen Maintenance application note for more details on Cree's lumen maintenance testing and forecasting. Please read the Thermal Management application note for details on how thermal design, ambient temperature, and drive current affect the LED junction temperature.

Moisture Sensitivity

Cree recommends keeping XLamp MX-3 LEDs in the provided, resealable moisture-barrier packaging (MBP) until immediately prior to soldering. Unopened MBPs that contain XLamp LEDs do not need special storage for moisture sensitivity.

Once the MBP is opened, XLamp MX-3 LEDs should be handled and stored as MSL 2a per JEDEC J-STD-033, meaning they have limited exposure time before damage to the LED may occur during the soldering operation. The table on the right specifies the maximum exposure time in days depending on temperature and humidity conditions. LEDs with exposure time longer than the specified maximums must be baked according to the baking conditions listed below.

Tomn		Maximum Percent Relative Humidity					
Temp.	30%	40%	50%	60%	70%	80%	90%
35 °C	-	-	-	17	1	.5	.5
30 °C	-	-	-	28	1	1	1
25 °C	-	-	-	-	2	1	1
20 °C	-	-	-	-	2	1	1

Baking Conditions

It is not necessary to bake all XLamp MX-3 LEDs. Only the LEDs that meet all of the following criteria must be baked:

- 1. LEDs that have been removed from the original MBP.
- 2. LEDs that have been exposed to a humid environment longer than listed in the Moisture Sensitivity section above.
- 3. LEDs that have not been soldered.

LEDs should be baked at 70 °C for 24 hours. LEDs may be baked on the original reels. Remove LEDs from the MBP before baking. Do not bake parts at temperatures higher than 70 °C. This baking operation resets the exposure time as defined in the Moisture Sensitivity section above.



NOTES - CONTINUED

Storage Conditions

XLamp MX-3 LEDs that have been removed from the original MBP but not soldered should be stored in one of the following ways:

- Store the parts in a rigid metal container with a tight-fitting lid. Verify that the storage temperature is <30 °C, and place fresh desiccant and an RH indicator in the container to verify that the RH is no greater than 60%.
- Store the parts in a dry, nitrogen-purged cabinet or container that actively maintains the temperature at <30° and the RH at no greater than 60%.
- For short-term store only: LEDs can be resealed in the original MBP soon after opening. Fresh desiccant may be needed. Use the included humidity indicator card to verify <60% RH.

If an environment of <60% RH is not available for storage, XLamp MX-3 LEDs should be baked (described above) before reflow soldering.

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

UL Recognized Component

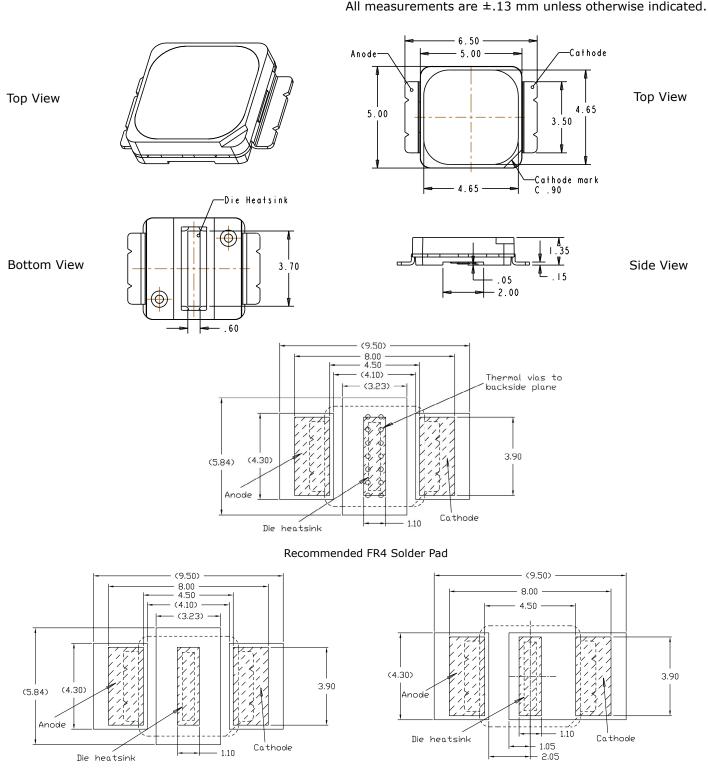
Level 4 enclosure consideration. The LED package or a portion thereof has been investigated as a fire and electrical enclosure per ANSI/UL 8750.

Vision Advisory

WARNING: Do not look at exposed lamp in operation. Eye injury can result. For more information about LEDs and eye safety, please refer to the LED Eye Safety application note.



MECHANICAL DIMENSIONS



Recommended MCPCB Solder Pad

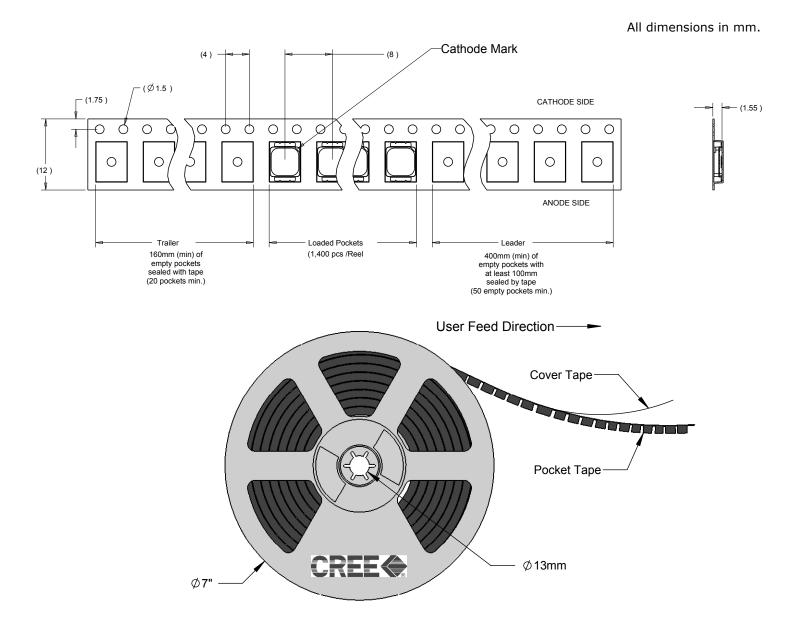
Alternative Solder Pad

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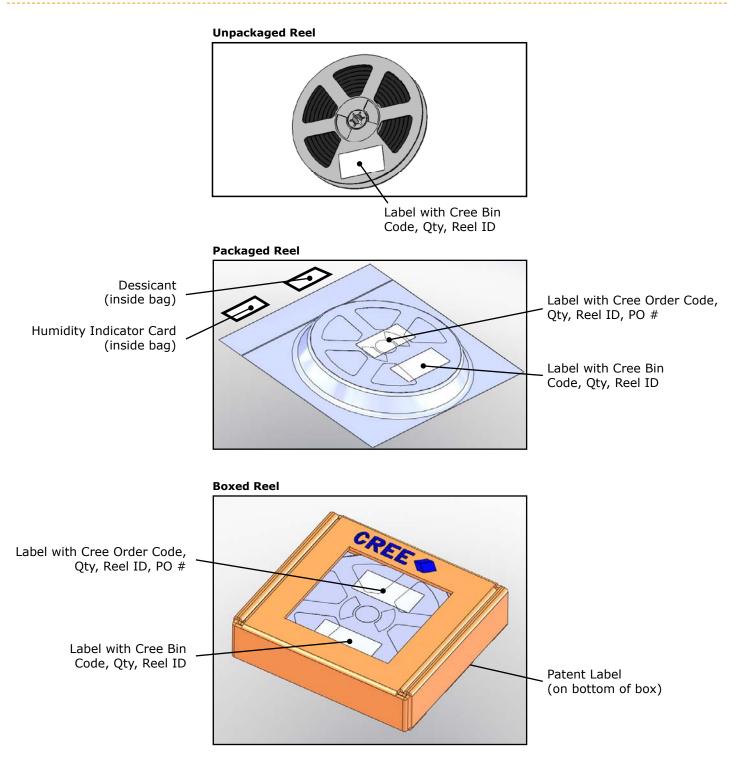
TAPE AND REEL

All Cree carrier tapes conform to EIA-481D, Automated Component Handling Systems Standard.





PACKAGING



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Cree, Inc.:

,			
MX3AWT-A1-0000-0007A9	9 MX3AWT-A1-0000-0007AA	A MX3AWT-A1-0000-0007B	MX3AWT-A1-0000-0007B9
MX3AWT-A1-0000-0007E8	MX3AWT-A1-0000-0008A5	MX3AWT-A1-0000-0008A6	MX3AWT-A1-0000-0008A7
MX3AWT-A1-0000-0008A8	MX3AWT-A1-0000-0008A9	MX3AWT-A1-0000-0008AA	MX3AWT-A1-0000-0008B4
MX3AWT-A1-0000-0008B5	MX3AWT-A1-0000-0008B6	MX3AWT-A1-0000-0008B7	MX3AWT-A1-0000-0008B8
MX3AWT-A1-0000-0008B9	MX3AWT-A1-0000-0008E6	MX3AWT-A1-0000-0008E7	MX3AWT-A1-0000-0008E8
MX3AWT-A1-0000-0008F6	MX3AWT-A1-0000-0008F7	MX3AWT-A1-0000-0008F8	MX3AWT-A1-0000-0009A5
MX3AWT-A1-0000-0009A6	MX3AWT-A1-0000-0009A7	MX3AWT-A1-0000-0009A8	MX3AWT-A1-0000-0009A9
MX3AWT-A1-0000-0009AA	MX3AWT-A1-0000-0009B4	MX3AWT-A1-0000-0009B5	MX3AWT-A1-0000-0009B6
MX3AWT-A1-0000-0009B7	MX3AWT-A1-0000-0009B8	MX3AWT-A1-0000-0009B9	MX3AWT-A1-0000-0009E6
MX3AWT-A1-0000-0009E7	MX3AWT-A1-0000-0009E8	MX3AWT-A1-0000-0009F6	MX3AWT-A1-0000-0009F7
MX3AWT-A1-0000-0009F8	MX3AWT-A1-0000-000AA1	MX3AWT-A1-0000-000AA2	MX3AWT-A1-0000-000AA3
MX3AWT-A1-0000-000AA4	MX3AWT-A1-0000-000AA5	MX3AWT-A1-0000-000AA6	MX3AWT-A1-0000-000AA7
MX3AWT-A1-0000-000AA8	MX3AWT-A1-0000-000AA9	MX3AWT-A1-0000-000AAA	MX3AWT-A1-0000-000AB1
MX3AWT-A1-0000-000AB2	MX3AWT-A1-0000-000AB3	MX3AWT-A1-0000-000AB4	MX3AWT-A1-0000-000AB5
MX3AWT-A1-0000-000AB6	MX3AWT-A1-0000-000AB7	MX3AWT-A1-0000-000AB8	MX3AWT-A1-0000-000AB9
MX3AWT-A1-0000-000ADZ	MX3AWT-A1-0000-000AE3	MX3AWT-A1-0000-000AE4	MX3AWT-A1-0000-000AE5
MX3AWT-A1-0000-000AE6	MX3AWT-A1-0000-000AE7	MX3AWT-A1-0000-000AE8	MX3AWT-A1-0000-000AF4
MX3AWT-A1-0000-000AF5	MX3AWT-A1-0000-000AF6	MX3AWT-A1-0000-000AF7	MX3AWT-A1-0000-000AF8
MX3AWT-A1-0000-000B50	MX3AWT-A1-0000-000B51	MX3AWT-A1-0000-000B53	MX3AWT-A1-0000-000BA1
MX3AWT-A1-0000-000BA2	MX3AWT-A1-0000-000BA3	MX3AWT-A1-0000-000BA4	MX3AWT-A1-0000-000BA5
MX3AWT-A1-0000-000BA6	MX3AWT-A1-0000-000BA7	MX3AWT-A1-0000-000BA8	MX3AWT-A1-0000-000BB1
MX3AWT-A1-0000-000BB2	MX3AWT-A1-0000-000BB3	MX3AWT-A1-0000-000BB4	MX3AWT-A1-0000-000BB5
MX3AWT-A1-0000-000BB6	MX3AWT-A1-0000-000BB7	MX3AWT-A1-0000-000BDZ	MX3AWT-A1-0000-000BE3
MX3AWT-A1-0000-000BE4	MX3AWT-A1-0000-000BE5	MX3AWT-A1-0000-000BE6	MX3AWT-A1-0000-000BE7
MX3AWT-A1-0000-000BF4	MX3AWT-A1-0000-000BF5	MX3AWT-A1-0000-000BF6	MX3AWT-A1-0000-000BF7